Chip Scale Review

2016 Editorial Calendar

(Editorial close date: 11/20) — January • February — *(* denotes show distribution)*

Packaging trends	• **SEMI ISS (Industry Strategy Symposium** Half Moon Bay, CA (Jan 10-13)
Assembly materials	• **SEMI European 3D Summit** Grenoble, France (Jan 18-20) *
Advanced underfills for nex-gen flip chip applications	• **SMTA Pan Pac Microelectronics Symposium *** Kohala Coast, Hawaii (Jan 25-28)
Wafer carrier solutions	• **SEMICON Korea** Seoul, Korea (January 27-29)
3D package reliability	• **BiTS Workshop *** Mesa, AZ (March 6-9)
Metrology for 3D integration	• **APEX Expo** Las Vegas, NV (March 15-17)
Advances in wafer probing	• **IMAPS Device Packaging (DPC) *** Fountain Hills, AZ (March 15-17)
Reducing the cost of test	• **SEMICON China* Productronica China** Shanghai China (March 15-17)
Socket contact technologies	

International Directory of Test and Burn-in Socket Suppliers

Ad Space Close Jan 22 - Ad Materials Deadline Jan 29

(Editorial close date: 12/19) — March • April

MEMS / sensors update	• **SEMICON South East Asia** Penang, Malaysia (Apr 26-28)
Cu pillar technology	• **MEPTEC** **MEMS Technology Symposium *** San Jose, CA (TBD) **IoT Symposium *** San Jose, CA (TBD)
Flexible substrates	• **ECTC *** Las Vegas, NV (May 31- June 3)
FOWLP	
Die-to-wafer stacking	
Heterogeneous integration	
Packaging of high-power devices	
Glass interposers	
TSV technologies	

Ad Space Close Feb 19 - Materials Close Feb 26

(Editorial close date: 3/11) — May • June

Industry market update	• **IMAPS Advanced Technology Workshop *** Dearborn, MI (TBD)
Package optimization & failure analysis with 3D X-ray	• **IEEE/SW Test Workshop (SWTW)** San Diego, CA (TBD)
Failure analysis methodologies for advanced packaging	• **SEMI Europe Packaging Tech Seminar *** Porto, Portugal (TBD)
Multi-chip packaging technology advances	• **SEMICON West *** San Francisco, CA (July 12-14)
Ultra-thin embedded packaging	
Metrology for advanced packaging	
Packaging materials update	
3D integration for tomorrow's devices	
Lithography challenges	

Ad Space Close May 20 - Ad Materials Close May 27

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Notes: Editorial calendar topics and distribution are subject to change without notice and are contingent on logistics and magazine production.